

<b>Notice of References Cited</b>	Application/Control No. 10/034,757	Applicant(s)/Patent Under Reexamination STRAND ET AL.	
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**U.S. PATENT DOCUMENTS**

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Name	Classification
	A	US-			
	B	US-			
	C	US-			
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**FOREIGN PATENT DOCUMENTS**

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	Q					
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	S					
	T					

**NON-PATENT DOCUMENTS**

*		Include as applicable: Author, Title Date, Publisher, Edition or Volume, Pertinent Pages)
	U	Reactions of high lead solders with BIOACT EC-7R semi-aqueous cleaning reagents Wong, C.P.; Gillum, W.O.; Walters, R.A.; Sakach, P.J.; Powell, D.; Bivins, B.; Components, Packaging, and Manufacturing Technology, Part C, IEEE Transactions on [see also Compo
	V	Diffusion of low molecular weight fluid in EPDM Liwen Cao; Hackam, R.; Electrical Insulation and Dielectric Phenomena, 1998. Annual Report. Conference on , Volume: 1 , 25-28 Oct. 1998
	W	An integrated LC-ESI chip with electrochemical-based gradient generation Jun Xie; Jason Shih; Changlin Pang; Yu-Chong Tai; Yunan Miao; Lee, T.D.; Micro Electro Mechanical Systems, 2004. 17th IEEE International Conference on. (MEMS) , 2004
	X	

\*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)  
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